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## FACSIMILE COVER SHEET

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**DATE:** June 1, 2004  
**FILE NO:** AMAT/5262/CMP/CMP/RKK  
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**FROM:** Keith M. Tackett  
**PAGE(S) with cover:** 2  
**ORIGINAL TO FOLLOW?** ☐ YES ☒ NO

### SECOND RESPONSE TO FINAL OFFICE ACTION DATED FEBRUARY 6, 2004

**TITLE:** Method and Apparatus For Forming Metal Layers  
**U.S. SERIAL NO.:** 09/961,134  
**FILING DATE:** September 21, 2001  
**INVENTOR:** Tsai, et al.  
**EXAMINER:** Edna Wong  
**GROUP ART UNIT:** 1753  
**CONFIRMATION NO.:** 4110

#### CONFIDENTIALITY NOTE

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**IN THE CLAIMS:**

The status of the claims is as follows:

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1-23. (Cancelled)

24. (Previously Presented): A method of forming a metal layer on a substrate, comprising:

positioning a substrate in an electroplating cell having a porous pad and an electrolyte solution therein;

contacting at least a portion of the substrate to the porous pad;

forming a metal layer on the substrate by biasing the substrate relative to an electrode at a first electrical bias and then biasing the substrate relative to the electrode at a second electrical bias, wherein the first electrical bias deposits metal on the substrate and the second electrical bias removes metal from the substrate; and

varying the magnitude of the second electrical bias relative to the first electrical bias as the metal layer is formed.

25. (Cancelled)